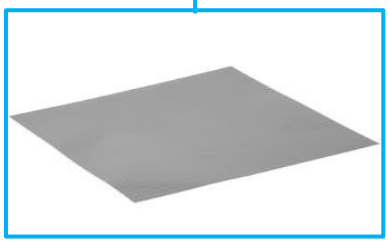
Thermal Foils & Films

FT_TFO_012_D_30



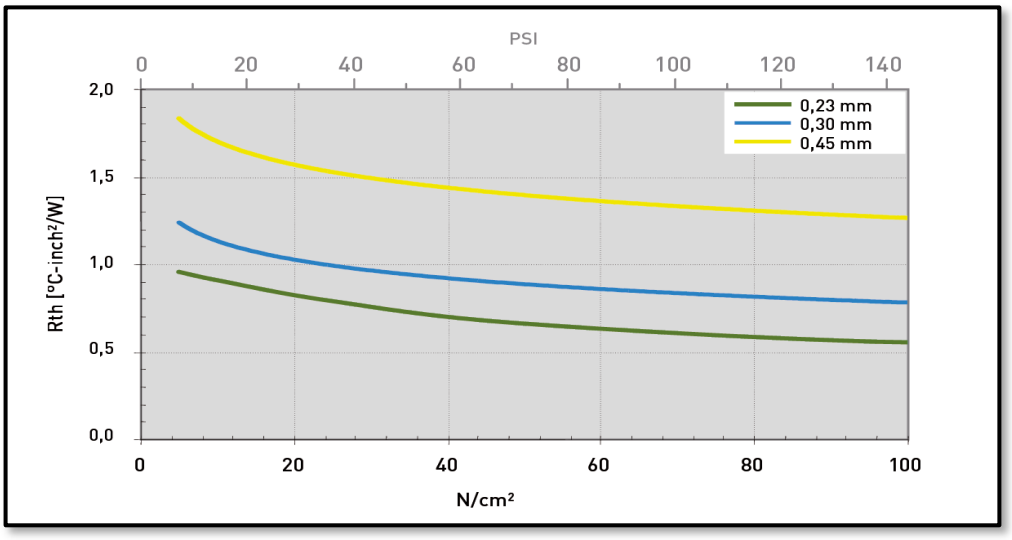
Our Thermal Foams also called Graphic Interfaces are silicone-based thermo-conductive materials that solve the problems of heat dissipation. TFO_012_D is a specially developed heat dissipation in silicone sheet for applications where low cooling requirements are required. Indeed, it is an excellent thermal conductor of 1.2W/mK, with good thermal resistance facilitating heat transfer and does not have electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

Application Areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR Module, etc.

Technical Characteristics

Features	Units	TFO_012_D			
Thickness	mm	0.23	0.30	0.45	-
Reinforcement	-	Fiberglass			
Color	-	Gray			
Tensile strength	kpsi	5.00	4.10	2.90	-
Size	mm	320*1000			Roller 300mm*50m
Resistance @150 Psi	°C-inch²/W	0.55	0.75	1.25	-
Resistance @30 Psi		0.79	1.05	1.55	-
-	-	-			
Thermal Conductivity	W/mK	1.2			
Temperature	°C	-50 to 180			
Breakdown voltage	kV/AC	5.5	> 6.0		-
Volume resistance	0hm - cm	> 1.0 X 10^{11}			
Contante dielectric	@1MHz	6			

The TFO_012_D is available in 0.23/0.30/0.45mm thicknesses.



Results obtained under laboratory conditions and should be considered as a guide only. AB2E has no control over its customers' hardware and many other factors, it is the user's responsibility to perform their own tests to ensure that the product meets their needs.